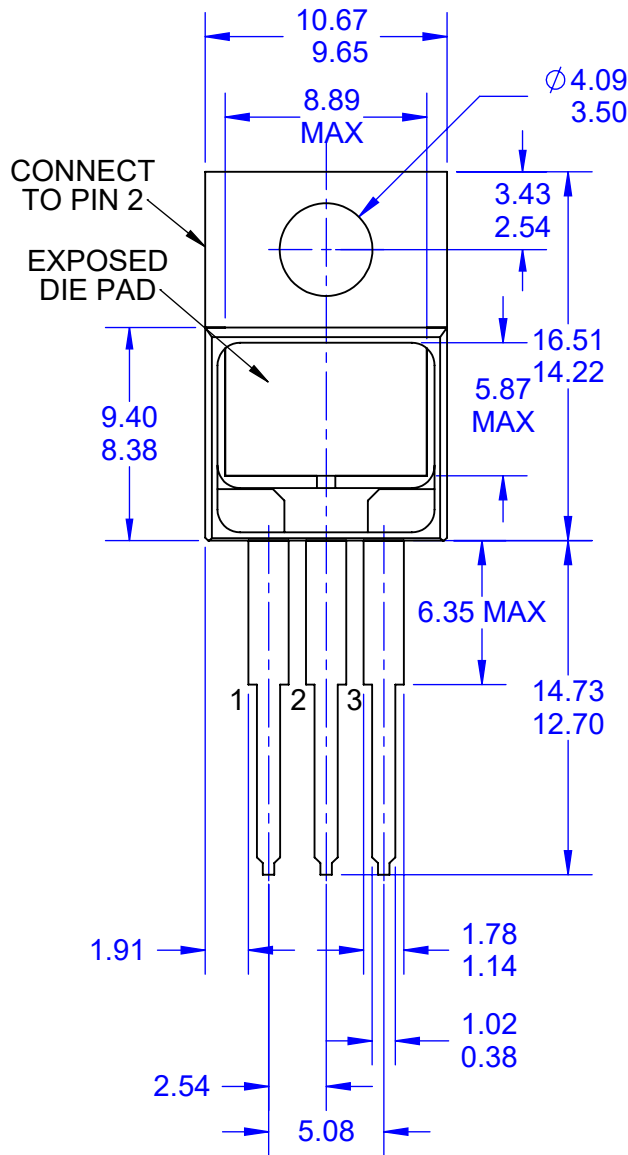
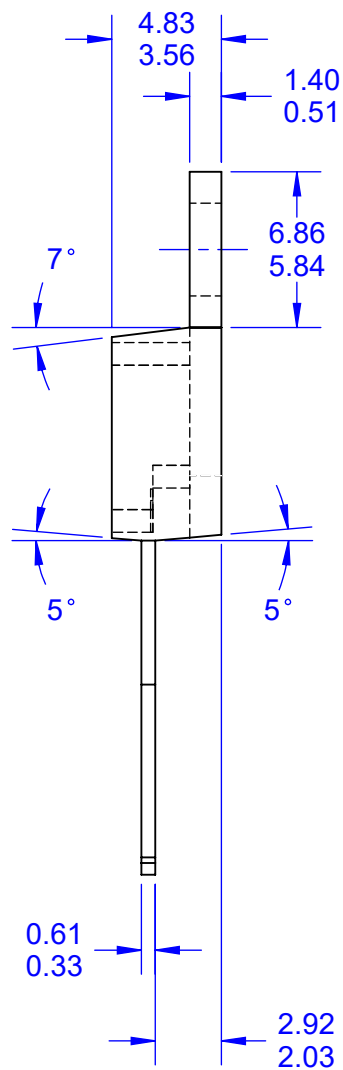


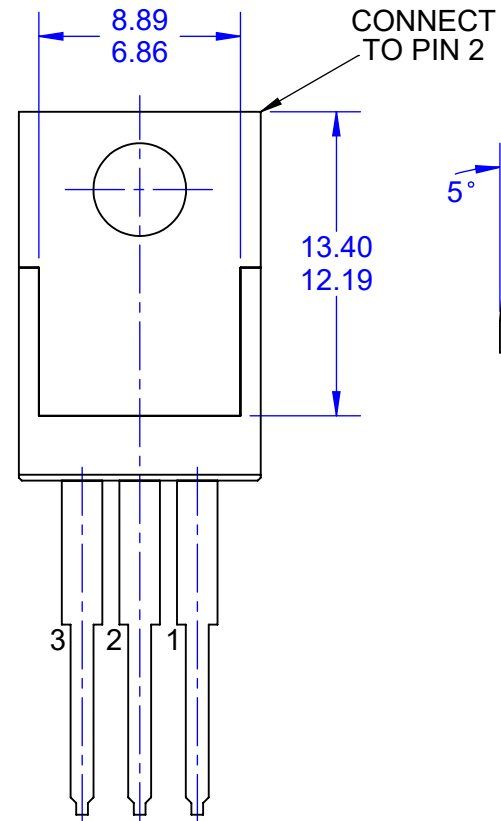
TOP VIEW



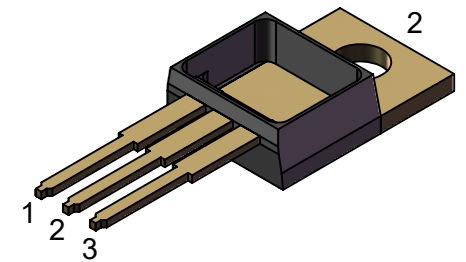
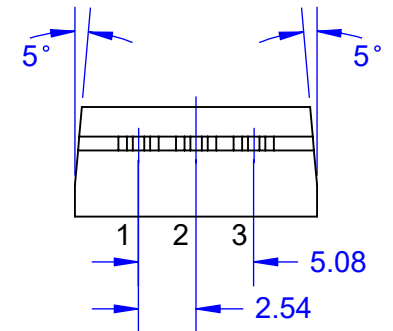
SIDE VIEW



BOTTOM VIEW




END VIEW



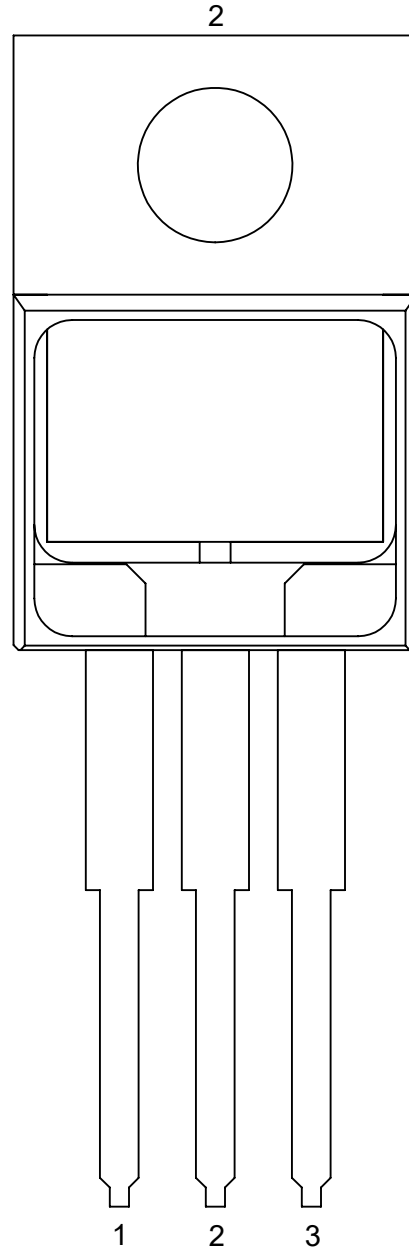
PERSPECTIVE VIEW

NOTES: (Unless Otherwise Specified).


- 1) DIMENSIONS IN mm.
- 2) BODY SEMICONDUCTOR GRADE MOLDING EPOXY.
- 3) LEAD FRAME: COPPER ALLOY A194.
- 4) PLATING THICKNESS: Ni 2.5~7.6 μ m Au 0.5~0.76 μ m.
- 5) DIE PAD SIZE: 5.87x8.89mm.

APPROVALS	DATE	 M-T0220-G3 OPEN CAVITY PACKAGE			
DRAWN T.Au	9/26/2021				
ENG M. Hart	9/26/2021	TITLE			
MFG		SCALE	SIZE	DRAWING NO.	REV
QA		3:1	A	122203	A
CUST		DO NOT SCALE DRAWING			SHEET 1 OF 3
REVISED					

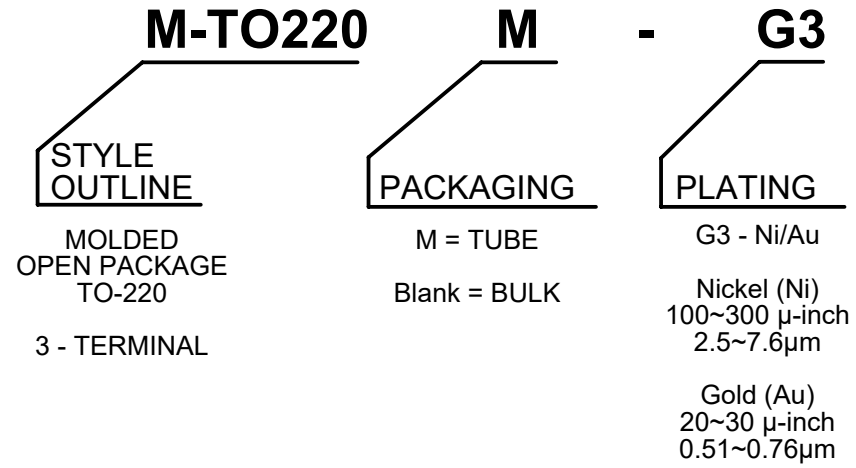
**INTERNAL WIRING CIRCUIT (JUMPER)
DAISY CHAIN PART NUMBER SUFFIX
TOP VIEW**



NOTE:
1) EXPOSED METAL HEAT SINK IS CONNECTED TO PIN 2.

 Mirror "forward the way"			
TITLE		M-T0220-G3 OPEN CAVITY PACKAGE	
SCALE	SIZE	DRAWING NO.	REV
5:1	A	122203	A
DO NOT SCALE DRAWING			SHEET 2 OF 3

PART NUMBERING SYSTEM



TITLE			
M-TO220-G3 OPEN CAVITY PACKAGE			
SCALE	SIZE	DRAWING NO.	REV
	A	122203	A
DO NOT SCALE DRAWING			SHEET 3 OF 3